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PATENT APPLICATION
ATTORNEY DOCKET NO. LMRX-P026/P1068

IN THE
UNITED STATES PATENT & TRADEMARK OFFICE

Applicant: HAO et al.

Application No. 10/672,085

Examiner: Unassigned

Filed: September 26, 2003

Group No. 3722

Title: Methods and Apparatus for Optimizing
the Delivery of a Set of Gases in a Plasma
Processing System

Confirmation No. 7062

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on February 26, 2004.

Signed: 

Sandra Halliwell

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

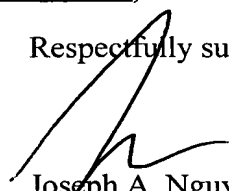
Dear Sir:

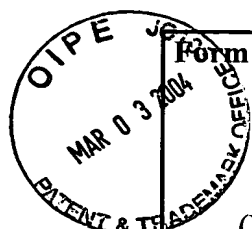
The references listed in the attached PTO Form 1449, copies of which are attached, may be material to the patentability of the referenced patent application. Applicants submit these references in compliance with their duty of disclosure pursuant to 37 CFR §§ 1.56 and 1.97. The Examiner is requested to make this citation of official record in this application.

This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the patentability of this application does not exist, or that this reference indeed constitutes prior art.

This Information Disclosure Statement is believed to be filed before the mailing date of a first Office Action on the merits. Accordingly, it is believed that no fees are due in connection with the filing of this Information Disclosure Statement. If it is determined that any additional fees are due to process this document, the Commissioner is hereby authorized to charge such fees to Deposit Account 502284 (Order No. LMRX-P026).

Respectfully submitted,


Joseph A. Nguyen
Reg. No. 37,899



Form 1449 (Modified)

**Information Disclosure
Statement By Applicant**

(Use Several Sheets if Necessary)

Atty Docket No.
LMX-P026/P1068

Application No.:
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Applicant:
Hao et al.

Filing Date
09/26/2003

Group
3722

U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	1	Henderson, et al., "Cylinder Package effects on the purity of the electronic specialty gases" (June 1997) Unknown publisher, Vol 40, Iss. 6, 3 pp
	2	www.plastic-bottles-guide.com , "Blow Molding Techniques", (Sep 2003) 2 pp.
	3	www.dupont.com/teflon , "Techniques for Fabricating DuPont FEP Film – Heat Bonding", (Sep 2003) 2003 E.I. duPont de Nemours and Co., 4 pp.
	4	www.plasticsindustry.org/industry/process , "processing methods" (Sep 2003), 1999 The Society of the Plastics Industry, 4 pp.
	5	www.matweb.com , "AISI Type 316 Stainless Steel, annealed bar" (Sep 2003) 1996-2004 by Automation Creations, Inc., 3 pp.
	6	Entegris, "Teflon Material Data Sheet", 2002 Entegris, Inc., 2 pp.
	7	www.gordonengland.co.uk , "Corrosion – The Corrosion Process" (Sep 2003) 9 pp.
	8	Saleem et al., "Ultrapure Materials – Gases: Examining the corrosion resistance of chromium-passivated stainless-steel tubes", (Sep 2003) 1997-2003 Canon Communications LLC, www.micromagazine.com/archive
	9	Collins et al., "Stainless Steel for Semiconductor Applications", (Oct 1997) 39 th Mech. Working & Steel Proc. Conference Proceedings of the Iron & Steel Soc., 1998, pp. 607-19
	10	Collins, "Stainless Steels for Semiconductor Gas Applications", (Jul/Aug 2002), Gases and Technology, pp. 10-15
	11	www.mcnallyinstitute.com , "Corrosion problems associated with stainless steel 4-1", (Sep 2003)
Examiner		Date Considered

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.